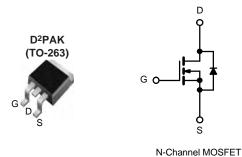


NTB75N03L09T4G-VB Datasheet N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY							
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, e}	Q _g (Typ)				
30	0.0024 at V _{GS} = 10 V	98	82 nC				
	0.0027 at V _{GS} = 4.5 V	98	02 110				



FEATURES

- Trench Power MOSFET .
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2011/65/EU

APPLICATIONS

- OR-ing
- Server
- DC/DC •

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage	V _{GS}	± 20			
	T _C = 25 °C		98 ^{a, e}		
Continuous Drain Current (T 175 °C)	T _C = 70 °C		98 ^e		
Continuous Drain Current ($T_J = 175 \ ^{\circ}C$)	T _A = 25 °C	I _D	28.8 ^{b, c}	A	
	T _A = 70 °C		27 ^{b, c}		
Pulsed Drain Current	I _{DM}	300			
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	36	7	
Single Pulse Avalanche Energy	L = 0.1 mm	E _{AS}	64.8	V	
Continuous Source-Drain Diode Current	T _C = 25 °C	1-	90 ^{a, e}	٨	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.13 ^{b, c}	— A	
	T _C = 25 °C		250 ^a		
Maria Dissistation	T _C = 70 °C	P	175		
Maximum Power Dissipation	T _A = 25 °C	P _D	3.75 ^{b, c}	W	
	T _A = 70 °C		2.63 ^{b, c}		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Тур.	Max.	Unit		
Maximum Junction-to-Ambient ^{b, d}	$t \le 10 \text{ sec}$	R _{thJA}	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	0,00		

Notes:

a. Based on $T_C = 25 \text{ °C}$. b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 sec.
d. Maximum under steady state conditions is 90 °C/W.
e. Calculated based on maximum junction temperature. Package limitation current is 90 A.



SPECIFICATIONS ($T_J = 25 \text{ °C}$, Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	Cymbol			Typ.	Max.	Onic	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			35			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 7.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.5	-	2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 V, V_{GS} = 10 V$	90			Α	
		V _{GS} = 10 V, I _D = 28.8 A		0.0024			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 27 A		0.0027		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 28.8 A		160		S	
Dynamic ^b							
Input Capacitance	C _{iss}			12065			
Output Capacitance	C _{oss}	V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz		1725		pF	
Reverse Transfer Capacitance	C _{rss}			970			
Tatal Oata Ohanna	0	V_{DS} = 15 V, V_{GS} = 10 V, I_{D} = 28.8 A		171	257	nC	
Total Gate Charge	Qg	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 28.8 A		81.5	123		
Gate-Source Charge	Q _{gs}			34			
Gate-Drain Charge	Q _{gd}			29			
Gate Resistance	Rg	f = 1 MHz		1.4	2.1	Ω	
Turn-On Delay Time	t _{d(on)}			18	27		
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.625 Ω		11	17	- - - ns	
Turn-Off Delay Time	t _{d(off)}	$I_{D}\cong$ 24 A, V_{GEN} = 10 V, R_{g} = 1 Ω		70	105		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			55	83		
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.67 Ω		180	270		
Turn-Off Delay Time	t _{d(off)}	$\rm I_D\cong$ 22.5 A, $\rm V_{GEN}$ = 4.5 V, $\rm R_g$ = 1 Ω		55	83	1	
Fall Time	t _f			12	18		
Drain-Source Body Diode Characteristic	S			•			
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			90	A	
Pulse Diode Forward Current ^a	I _{SM}				90	Л	
Body Diode Voltage	V _{SD}	I _S = 22 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 20 A, di/dt = 100 A/μs, T _J = 25 °C		70.2	105	nC	
Reverse Recovery Fall Time	t _a	$r_{\rm F} = 20$ A, $a_{\rm F}a_{\rm C} = 100$ A/ μ s, $r_{\rm J} = 20$ C		27		ns	
Reverse Recovery Rise Time	t _b			25			

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

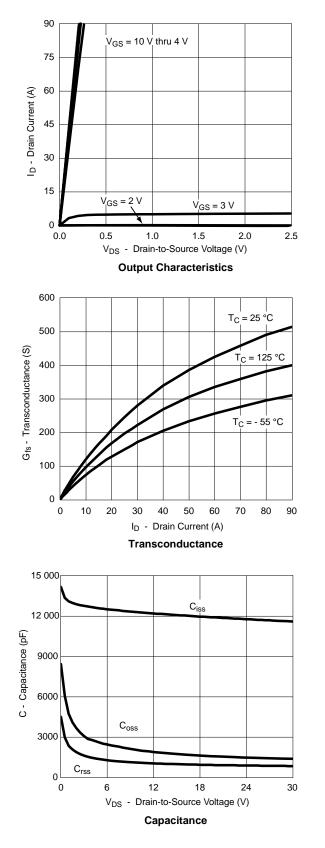
b. Guaranteed by design, not subject to production testing.

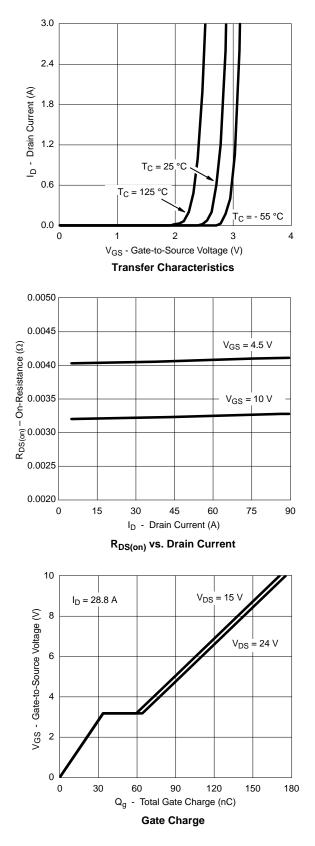
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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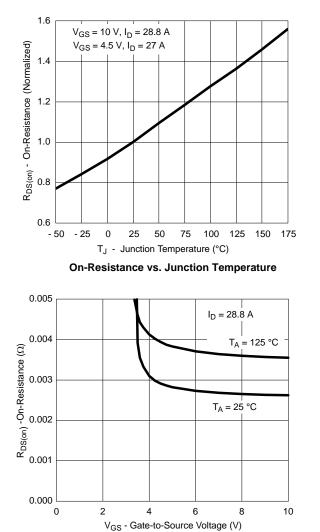
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

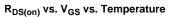


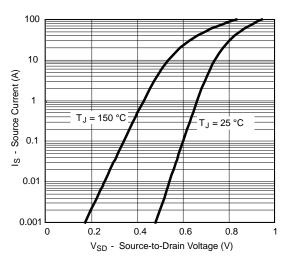




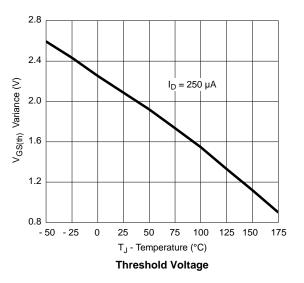
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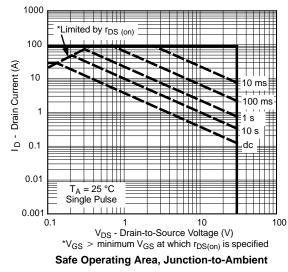




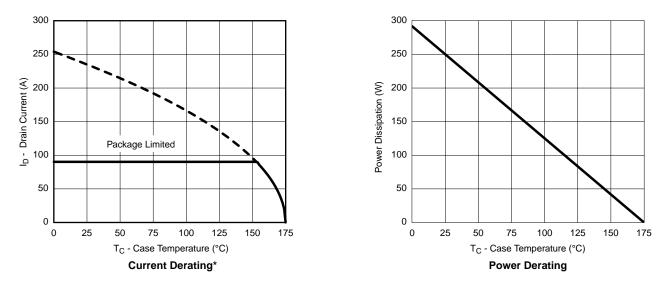


Forward Diode Voltage vs. Temperature



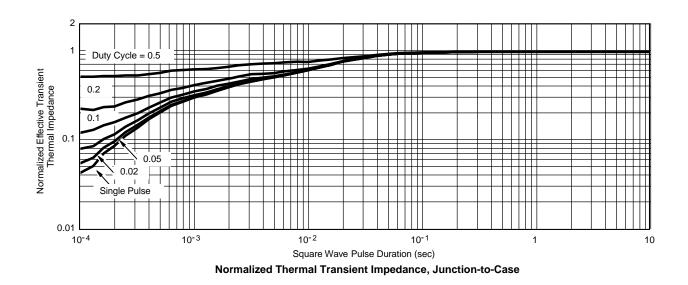






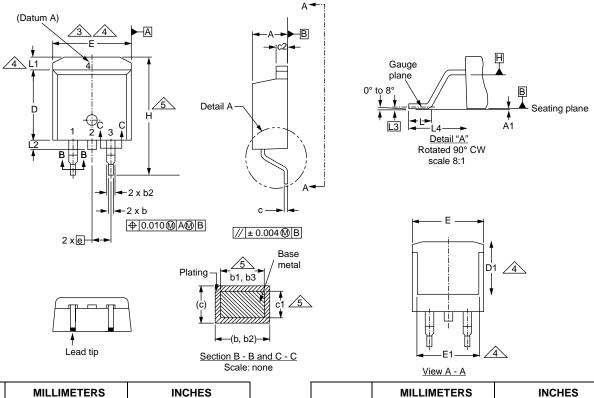
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

*The power dissipation P_D is based on $T_{J(max)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





TO-263AB (HIGH VOLTAGE)



	MILLIMETERS		INCHES			MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.	DIM.	MIN.	MAX.	MIN.	MAX.
А	4.06	4.83	0.160	0.190	D1	6.86	-	0.270	-
A1	0.00	0.25	0.000	0.010	E	9.65	10.67	0.380	0.420
b	0.51	0.99	0.020	0.039	E1	6.22	-	0.245	-
b1	0.51	0.89	0.020	0.035	e	2.54 BSC		0.100 BSC	
b2	1.14	1.78	0.045	0.070	Н	14.61	15.88	0.575	0.625
b3	1.14	1.73	0.045	0.068	L	1.78	2.79	0.070	0.110
с	0.38	0.74	0.015	0.029	L1	-	1.65	-	0.066
c1	0.38	0.58	0.015	0.023	L2	-	1.78	-	0.070
c2	1.14	1.65	0.045	0.065	L3	0.25 BSC		0.010 BSC	
D	8.38	9.65	0.330	0.380	L4	4.78	5.28	0.188	0.208
ECN: S-82 DWG: 597	2110-Rev. A, 0	15-Sep-08	1	•	•	•	1	•	•

Notes

2. Dimensions are shown in millimeters (inches).

3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.

4. Thermal PAD contour optional within dimension E, L1, D1 and E1.

5. Dimension b1 and c1 apply to base metal only.

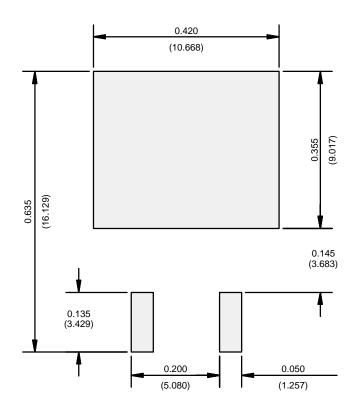
6. Datum A and B to be determined at datum plane H.

7. Outline conforms to JEDEC outline to TO-263AB.

^{1.} Dimensioning and tolerancing per ASME Y14.5M-1994.



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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